

After page 15, please insert the following abstract:

--Abstract of the Invention


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A support and tensioning frame for a stencil to enable solder paste to be applied to printed circuit boards and other electronic substrates comprising a support frame having four side members with at least two opposing side members having a stencil support surface which the stencil abuts and over which the stencil is flexed by two displaceable mounting bars disposed within opposing side members. The mounting bars are engaged with the stencil by a plurality of projections extending from a terminal edge of a mounting plate comprising each mounting bar which are sized for receipt by a plurality of apertures disposed along at least two side edges of the stencil. Each mounting bar is biased in an outwardly position by a plurality of compression springs disposed along each side member. Mounting bars are simultaneously displaced for engagement and disengagement of the stencil by an inflatable tubular member disposed within each side member and extending through all four side members of the support frame when the tubular member is inflated with air.--

REMARKS

This preliminary amendment is submitted in order to correct informalities in the form of the specification as filed. Applicant believes that the abstract submitted herein does not contain new subject matter and meets the requirement pursuant to 37 C.F.R. §1.72(b).

Early examination and favorable consideration of the above-identified application is earnestly solicited. If the Examiner has any questions concerning this application, the Examiner is invited to telephone Applicant's attorney at the number provided below.


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